Contact Name   Title - Contact   Phone - Cont	IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name	752-21.1										als and Mf	g Informat	ion		
Internate Name  Title - Contact  Phone - Contact*  Phone - Contact*  Product-Env-Stewards  Product Enviro Compliance  Title - Representative  Title - Representative  Phone - Representative*  Product-Env-Stewards  Product	upplier Infor	mation				•									
Title - Contact Name Product Env-Stewards Product Env-Stewards Product Enviro Compliance Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Na Product-Env-Stewards Nanufacturing Site Product-Env-Stewards Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Site Nanufacturing Proccess Information  Product-Env-Stewards Nanufacturing Proccess Information  Product-Env-Stewards Nanufacturing Site Nanufact	Company name* Company union				ique ID U1			Unique ID Authority				Response Date*			
Product Env-Stewards	nsemi										2023-06-08				
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed  Title - Representative Phone - Representative* NA Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM Manufacturing Proccess Information  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds  Seconds  Seconds  Seconds  Seconds  Matter Tin (Sn) - annealed  Max Time at Peak Temperature Number of Reflow Cycles Seconds  Seconds  Matter Tin (Sn) - annealed  Max Time at Peak Temperature Number of Reflow Cycles Seconds  Max Time Alloy Number of Reflow Cycles Seconds	ontact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product Envr-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  NCP301LSN30T1G ANA UNDERVOLT DETECT 3.0V 2023-06-08 MY1 14.08 mg  Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Ter	Product-Env-Stev	wards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	uthorized Repre	sentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
NCP301LSN30T1G   ANA UNDERVOLT DETECT 3.0V   2023-06-08   MY1   14.08   mg	Product-Env-Stev	wards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Anufacturing Proccess Information  Terminal Plating / Grid Array Material  Matte Tin (Sn) - annealed  CU Alloy  Terminal Base Alloy  J-STD-020 MSL Rating Peak Process Body Temperature Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260  C 30  Seconds 3	Reques	Requester Item Number Mfr Ite		Number	Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	V	Veight*	UOM	Unit Type
Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  260  Comments			NCP301I	LSN30T1G	ANA UNDERVOI	LT DETECT 3	.0V	2023-06-08		N	IY1	1-	4.08	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments				arminal Reso	Alloy	STD 020 MS1	Pating	Dank Droo	ace Rody To	amparatur	May Time at Pook	Tamparatu	ira Numb	per of Paflow Cy	lac
omments	2 ,			•		L Kanng						ber of Kellow Cyc	ies		
		ı iii (Sii) - aiiilealeu	C	O Alloy	1			200		<u> </u>	30	second	18 3		
		time at neals townt	no dumina1	domina ia 10-1	10 seconds										
vel 1 - maximum time at peak temperature during soldering is 10-30 seconds or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.42	mg	Supplier	Silicon (Si)	7440-21-3		0.42	mg
Die Attach	0.11	mg		Epoxy resin	proprietary data		0.033	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.033	mg
			Supplier	2,2'-[[2-(oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bisoxirane	13561-08-5		0.033	mg
			Supplier	4-Methyl-2-Phenyl-1H-Imidazole	827-43-0		0.0099	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0011	mg
Lead Frame	5.78	mg	Supplier	Silver (Ag)	7440-22-4		0.0705	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0069	mg
			Supplier	Iron (Fe)	7439-89-6		0.1358	mg
			Supplier	Copper (Cu)	7440-50-8		5.565	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.367	mg
			Supplier	Phenolic Resin	Proprietary Data		0.367	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1468	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.4225	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.04	mg	Supplier	Gold (Au)	7440-57-5		0.04	mg